

0.5 kHz to 125 MHz, MHz-to-kHz Programmable Clock

Features

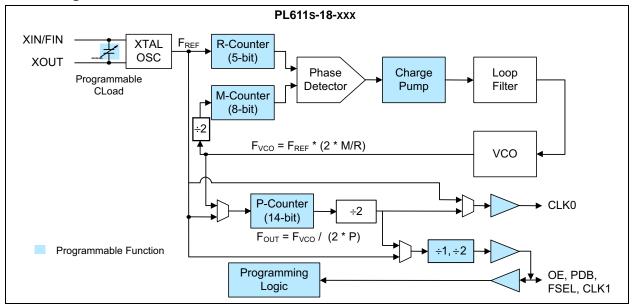
- · Designed for Very Low Power Applications
- Accepts Crystal or Reference Clock Inputs
- Input Frequency:
 - Fundamental Crystal: 10 MHz to 50 MHz
 - Reference Input: 1 MHz to 125 MHz
- Accepts >0.1V Reference Signal Input Voltage
- Output Frequency 0.5 kHz to 125 MHz CMOS
 - 65 MHz at 1.8V Operation
 - 90 MHz at 2.5V Operation
 - 125 MHz at 3.3V Operation
- One Programmable I/O Pin Can be Configured as OE, PDB, FSEL, or CLK1
- Low Current Consumption
- <1.0 mA with 27 MHz and 32 kHz Outputs
- <5 µA when PDB is Activated
- Single 1.8V ~ 3.3V, ±10% Power Supply
- Operating Temperature Range:
 - -40°C to +85°C (Industrial)
- 0°C to +70°C (Commercial)
- Available in 6-pin TDFN or SOT-23 GREEN/RoHS-Compliant Packaging

General Description

The PL611s-18-xxx is a general purpose frequency synthesizer and a member of the PicoPLL family, the world's smallest programmable clocks. PL611s-18-xxx offers the versatility of using a single crystal (MHz) or reference clock input and producing up to two (kHz/MHz) system clocks, or a combination of reference and frequency low outputs. The PL611s-18-xxx is designed for low-power applications with very stringent space requirements and consumes, for example, ~1.0 mA while producing two distinct outputs of 27 MHz and 32 kHz. The power down feature of the PL611s-18-xxx, when activated, allows the IC to consume less than 5 µA of power.

The PL611s-18-xxx fits in a small DFN-6L or SOT23-6L package. Cascading of the PL611s-18-xxx with other programmable clocks allows the generation of system level clocking requirements, thereby reducing the overall system implementation cost.

In addition, one programmable I/O pin can be configured as Output Enable (OE), Frequency switching (FSEL), Power Down (PDB) input, or CLK1 (CLK0, FREF, FREF/2) output.



Block Diagram

1.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings †

Supply Voltage (V _{DD})	–0.5V to +4.6V
Input Voltage (V _{IN})	
Output Voltage (V _{OUT})	
ESD Rating (Note 1)	

Operating Ratings ‡

Supply Voltage (V _{IN})+1.	1.62V to +3.63V
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† Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operational sections of this specification is not intended. Exposure to maximum rating conditions for extended periods may affect device reliability. Parts are tested to commercial grade only.

‡ Notice: The device is not guaranteed to function outside its operating ratings.

Note 1: Devices are ESD sensitive. Handling precautions are recommended. Human body model, 1.5 k Ω in series with 100 pF.

TABLE 1-1: DC ELECTRICAL CHARACTERISTICS (Note 1)

Electrical Characteristics: V_{IN} = 3.3V; C_L = 15 pF; T_A = +25°C, **bold** values indicate -40°C ≤ T_A ≤ +85°C, unless noted.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
		_	3.95	10.0		V _{DD} = 3.3V, 27 MHz Xtal input, F _{VCO} = 81 MHz, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 15 pF
Supply Current, Power Down State	I _{DD}	_	2.35	3.5	mA	V _{DD} = 2.5V, 27 MHz Xtal input, F _{VCO} = 81 MHz, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 10 pF
		_	1.30	2.0		V _{DD} = 1.8V, 27 MHz Xtal input, F _{VCO} = 81 MHz, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 5 pF
	I _{DD}	_	2.75	9.0		V _{DD} = 3.3V, 27 MHz Xtal input, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 15 pF
PLL Off Supply Current, Dynamic		_	1.30	2.0	mA	V _{DD} = 2.5V, 27 MHz Xtal input, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 10 pF
		_	0.9	1.4		V _{DD} = 1.8V, 27 MHz Xtal input, CLK0 = 32.768 kHz, CLK1 = 27 MHz, Load = 5 pF
Supply Current, Power Down State	I _{DD}	_		5	μA	When PDB = 0
Operating Voltage	V_{DD}	1.62	1	3.63	V	_
Output Current, Low Drive	I _{OLD}	4	_	—	mA	
Output Current, Standard Drive	I _{OSD}	8	_	—	mA	$V_{OL} = 0.4V, V_{OH} = V_{DD} - 0.9V,$ $V_{DD} = 3.3V$
Output Current, High Drive	I _{OHD}	16	_	—	mA	

Note 1: Specification for packaged product only.

TABLE 1-2: AC ELECTRICAL CHARACTERISTICS (Note 1)

Electrical Characteristics: V_{IN} = 3.3V; C_L = 15 pF; T_A = +25°C, **bold** values indicate –40°C ≤ T_A ≤ +85°C, unless noted.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Crystal Input Frequency	f _{IN(XTAL)}	10		50	MHz	Fundamental Crystal
		1		125		V _{DD} = 3.3V
Input Frequency	f _{IN}	1		90	MHz	V _{DD} = 2.5V
		1		65		V _{DD} = 1.8V
		0.8	_	V_{DD}		Internally AC-Coupled (high frequency)
Input (f _{IN}) Signal Amplitude	_	0.1	_	V _{DD}	V _{PP}	Internally AC-Coupled (low frequency) 3.3V ≤50 MHz, 2.5V ≤40 MHz, 1.8V ≤15 MHz
				125		V _{DD} = 3.3V
Output Frequency	f _{OUT}			90	MHz	V _{DD} = 2.5V
				65		V _{DD} = 1.8V

TABLE 1-2: AC ELECTRICAL CHARACTERISTICS (Note 1) (CONTINUED)

Electrical Characteristics: V_{IN} = 3.3V; C_L = 15 pF; T_A = +25°C, **bold** values indicate -40°C ≤ T_A ≤ +85°C, unless noted.

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Settling Time	_	_		2	ms	At power-up (after V _{DD} increases over 1.62V)
Output Enable Time	t _{OE}	—	_	100	μs	OE function; $T_A = +25^{\circ}C$, 15 pF load. Add one clock period for a usable output.
	01	_		2	ms	PDB function; T _A = +25°C, 15 pF load.
V _{DD} Sensitivity	—	-2		2	ppm	Frequency vs. V _{DD} ±10%
Output Rise Time	t _r	_	2	3	ns	15 pF load, 10/90% V _{DD} , Standard Drive, 3.3V
Output Fall Time	t _f	_	2	3	ns	15 pF load, 90/10% V _{DD} , Standard Drive, 3.3V
Duty Cycle	_	45	50	55	%	V _{DD} /2
Period Jitter, Peak-to-Peak (Note 2)			70		ps	With capacitive decoupling between V _{DD} and GND. 10,000 samples measured.

Note 1: Specification for packaged product only.

2: Jitter performance depends on the programming parameters.

TABLE 1-3: CRYSTAL SPECIFICATIONS

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions
Fundamental Crystal Resonator Frequency	F _{XIN}	10		50	MHz	—
Crystal Loading Rating (The IC can be programmed for any value in this range.)	C _{L(XTAL)}	8	_	12	pF	—
Maximum Sustainable Drive Level	_	—	_	100	μW	—
Operating Drive Level	_	_	30	_	μW	—
Metal Can Crystal Shunt Capacitance	C0	_		5.5	pF	_
Metal Can Crystal ESR max.	ESR	_	_	50	Ω	—
Small SMD Crystal Shunt Capacitance	C0	_		2.5	pF	—
Small SMD Crystal ESR max.	ESR	—	—	80	Ω	—

TEMPERATURE SPECIFICATIONS (Note 1)

Parameters	Sym.	Min.	Тур.	Max.	Units	Conditions				
Temperature Ranges										
Storage Temperature Range	T _S	-65	_	+150	°C	_				
Ambient Operating Temperature	T _A	-40	_	+85	°C	Industrial				
Ambient Operating Temperature	Τ _Α	0		+70	°C	Commercial				
Junction Operating Temperature	Τ _J	_		+110	°C	—				
Lead Temperature		_		+260	°C	Soldering, 10 sec.				
Thermal Resistance						•				
Junction Thermal Resistance, 6-Ld TDFN	θ_{JA}	—	100	—	°C/W	—				
Junction Thermal Resistance, 6-Ld SOT-23	θ_{JA}	—	192		°C/W	—				

Note 1: Exposure of the device under conditions beyond the limits specified by the maximum ratings for extended periods may cause permanent damage to the device and affect product reliability. These conditions represent a stress rating only, and functional operations of the device at these or any other conditions above the operational limits noted in this specification is not implied. Operating temperature is guaranteed by design. Parts are tested to commercial grade only.

2.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 2-1.

Pin Configurations

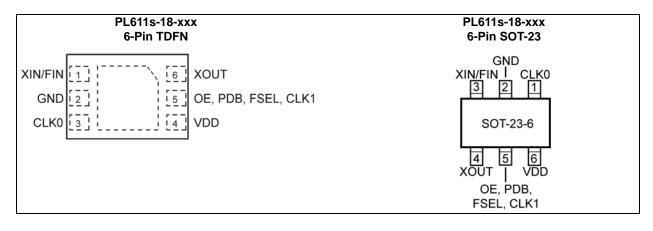


TABLE 2-1:	PIN FUNCTION TABLE
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6-Pin TDFN Pin Number	6-Pin SOT-23 Pin Number	Name	Туре	Description						
1	3	XIN, FIN	I	Crystal or refere	ence input pin.					
2	2	GND	Р	GND connection	n.					
3	1	CLK0	0	Programmable	clock output.					
4	6	VDD	Р	VDD connection	า.					
5	5	OE, PDB, FSEL, CLK1	I/O	This programmable I/O pin can be configured as an output enable (OE) input, power down (PDB) input, frequency select (FSEL) input, or CLK1 output. This pin has an internal 60 k Ω pull-up resistor on OE, PDB, and FSEL.						
				State OE PDB FSEL						
				0 Tri-State CLK Power Down Bank Mode			Bank 0			
				1 (default) Operating Operating Bank 1 Mode Mode						
6	4	XOUT	0	Crystal output p	Crystal output pin. Do not connect if FIN is used.					

3.0 FUNCTIONAL DESCRIPTION

PL611s-18-xxx is a highly featured, very flexible, advanced programmable PLL design for high performance, low-power, small form-factor applications. The PL611s-18-xxx accepts a crystal input of 10 MHz to 50 MHz or a reference clock input of 1 MHz to 125 MHz and is capable of producing two outputs up to 125 MHz. This flexible design allows the PL611s-18-xxx to deliver any PLL-generated frequency, F_{REF} (Crystal or Ref Clk) frequency or $F_{REF} \div (2 \times P)$ to CLK0 and/or CLK1.

3.1 PLL Programming

The PLL in the PL611s-18-xxx is fully programmable. The PLL is equipped with a 5-bit input frequency divider (R-Counter) and an 8-bit VCO frequency feedback loop divider (M-Counter). The output of the PLL is transferred to a 14-bit post-VCO divider (P-Counter). The output frequency is determined by the following formula:

EQUATION 3-1:

$$F_{OUT} = F_{REF} \times M \div (R \times P)$$

3.2 Clock Output (CLK0)

CLK0 is the main clock output. The PL611s-18-xxx can also be programmed to provide a second clock output, CLK1, on the programmable I/O pin (see the OE/PDB/FSEL/CLK1 field of Table 2-1). The output of CLK0 can be configured as the PLL output ($F_{VCO} \div (2 \times P)$), F_{REF} (Ref Clk Frequency) output, or $F_{REF} \div (2 \times P)$ output. The output drive level can be programmed to Low Drive (4 mA), Standard Drive (8 mA), or High Drive (16 mA). The maximum output frequency is 125 MHz. Because of the long P counter, the minimum output frequency is as low as 0.5 kHz.

3.3 Clock Output (CLK1)

The CLK1 feature allows the PL611s-18-xxx to have an additional clock output. This output can be programmed to one of the following:

- F_{REF}
- F_{REF} ÷ 2
- CLK0
- CLK0 ÷ 2

3.4 Output Enable (OE)

The Output Enable feature allows the user to enable and disable the clock output and PLL by toggling the OE pin. Because the crystal remains operational when the output is disabled, the output enable time is much faster than with the Power Down function. The OE pin incorporates a 60 k Ω pull up resistor giving a default condition of logic "1". Pulling the OE pin low "0" will tri-state the output buffers.

3.5 Power Down Control (PDB)

The Power Down (PDB) feature allows the user to put the PL611s-18-xxx into sleep mode. When activated (logic '0'), PDB disables the PLL, the oscillator circuitry, counters, and all other active circuitry and tri-state the output buffers. In Power Down mode the IC consumes <5 μ A of power. The PDB pin incorporates a pull-up resistor giving a default condition of logic "1".

3.6 Frequency Select (FSEL)

The Frequency Select (FSEL) feature allows the PL611s-18-xxx to switch between two pre-programmed outputs allowing the device on-the-fly frequency switching. The FSEL pin incorporates a 60 k Ω pull-up resistor giving a default condition of logic "1".

3.7 Programmable CLoad

The PL611s-18-xxx is equipped with programmable S-caps to allow the CLoad to be tuned from 8 pF to 12 pF.

4.0 LAYOUT RECOMMENDATIONS

The following guidelines are to assist you with a performance-optimized PCB design.

4.1 Signal Integrity and Termination Considerations

- · Keep traces short.
- Trace = Inductor. With a capacitive load this creates ringing.
- Long trace = Transmission Line. Without proper termination, this causes reflections that look like ringing.
- Design long traces (greater than one inch) as "striplines" or "microstrips" with defined impedance.
- Match the trace at one side to avoid reflections bouncing back and forth.

4.2 Decoupling and Power Supply Considerations

- Place decoupling capacitors as close as possible to the V_{DD} pin(s) to limit noise from the power supply.
- Multiple $\mathsf{V}_{\mathsf{D}\mathsf{D}}$ pins should be decoupled separately for best performance.

- The addition of a ferrite bead in series with V_{DD} can help prevent noise from other board sources.
- The value of the decoupling capacitor is frequency-dependent. Typical values to use are 0.1 μ F for designs using crystals <50 MHz and 0.01 μ F for designs using crystals >50 MHz.

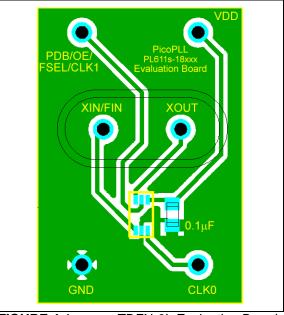
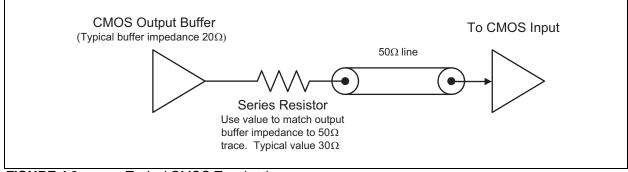
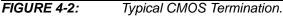


FIGURE 4-1: TDFN-6L Evaluation Board.

4.3 Typical CMOS Termination

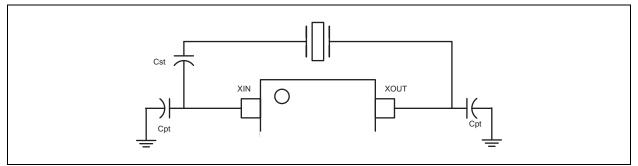
Place series resistor as close as possible to the CMOS output.





4.4 Crystal Tuning Circuit

Series and parallel capacitors are used to fine tune the crystal load to the circuit load.

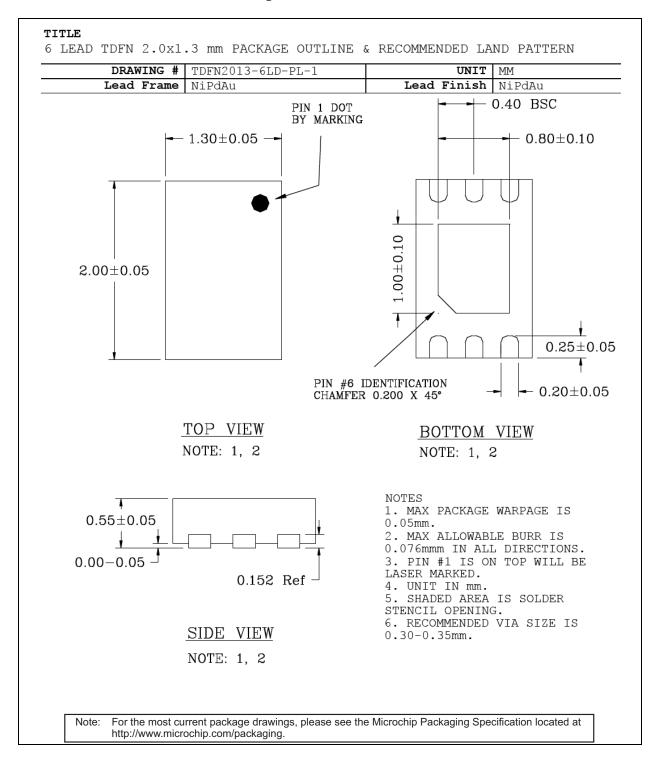


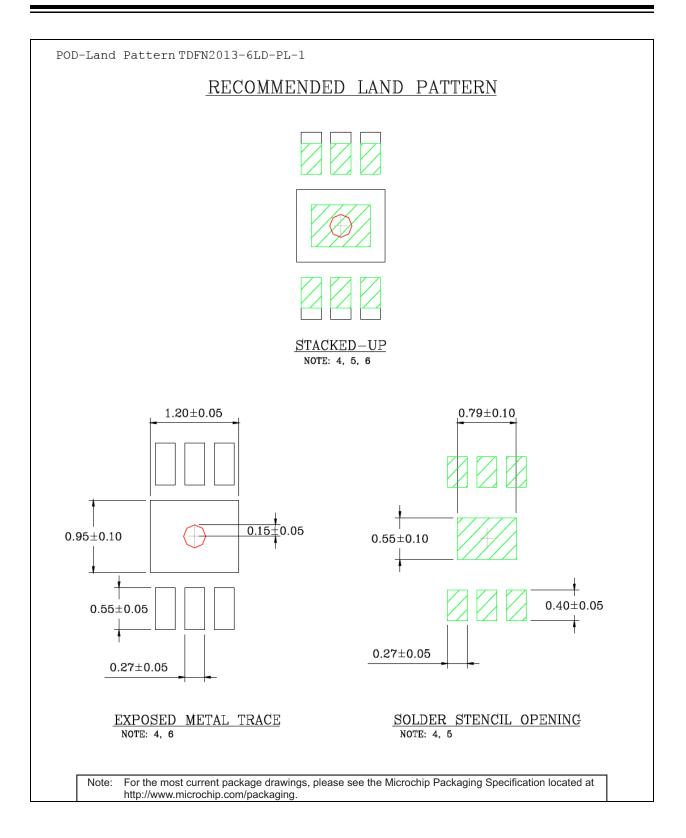
CST: Series capacitor, used to lower circuit load to match crystal load. Raises frequency offset. This can be eliminated by using a crystal with a CLoad of equal or greater value than the oscillator.

CPT: Parallel capacitors, used to raise the circuit load to match the crystal load. Lowers frequency offset.

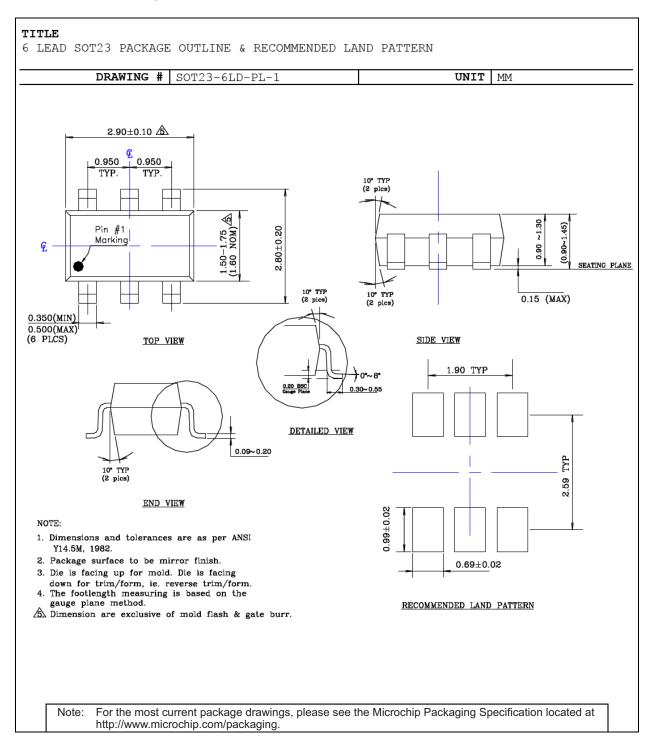
5.0 PACKAGING INFORMATION

6-Pin TDFN 2.0 mm x 1.3 mm Package Outline and Recommended Land Pattern





6-Pin SOT-23 Package Outline and Recommended Land Pattern



APPENDIX A: REVISION HISTORY

Revision A (March 2017)

- Converted Micrel document PL611s-18-xxx to Microchip data sheet DS20005741A.
- Minor text changes throughout.
- Updated part numbering conventions in the Product Identification System to be consistent with Microchip system.
- Added Commercial temperature range throughout document.
- Correct package outline drawing added for 6-lead TDFN in Packaging Information.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, contact your local Microchip representative or sales office.

		V V	E	Exa	mples:	
Device	O. — XXX X e ID Code Pack	x — X ☐ ☐ ☐ age Temperature Media Tyj		a)	PL611s-18-xxxGC:	0.5 kHz to 125 MHz, MHz-to-kHz Programmable Clock, ID Code, 6-Lead TDFN, Commercial Temp Range, 20/Bag
Device: ID Code:	ma	i kHz to 125 MHz, MHz-to-kHz Pro ble Clock Code will be assigned at time of	gram- b) I	PL611s-18-xxxGC-R:	0.5 kHz to 125 MHz, MHz-to-kHz Programmable Cloc ID Code, 6-Lead TDFN, Commercial Temp. Range, 3,000/Reel
Package:	G = 6-Lead T T = 6-Lead S	DFN	c	c) F	PL611s-18-xxxGI:	0.5 kHz to 125 MHz, MHz-to-kH. Programmable Clock, ID Code, 6-Lead TDFN, Industrial Temp. Range, 20/Bag
Temperature: Media Type:	I = -40° C to none = 20/Bag	′0°C (Commercial) +85°C (Industrial)	d	1) I	PL611s-18-xxxGI-R:	0.5 kHz to 125 MHz, MHz-to-kHz Programmable Cloo ID Code, 6-Lead TDFN, Industrial Temp. Range, 3,000/Reel
Part Marking	R = 3,000/Re (Note 1)	ei	e	e)	PL611s-18-xxxTC:	0.5 kHz to 125 MHz, MHz-to-kH Programmable Clock, ID Code, 6-Lead SOT-23, Commercial Temp. Range, 20/Bag
)	Marking XXX LLL	SOT-23 Marking 18XXX LLL	f)) [PL611s-18-xxxTC-R:	0.5 kHz to 125 MHz, MHz-to-kHz Programmable Clo ID Code, 6-Lead SOT-23, Commercial Temp. Range,
	. .	git number for the programmed, LL" designates a lot number.		g)	PL611s-18-xxxTI:	3,000/Reel 0.5 kHz to 125 MHz, MHz-to-kH Programmable Clock, ID Code, 6-Lead SOT-23, Industrial Temp Range, 20/Bag
			h	n) F	PL611s-18-xxxTI-R:	0.5 kHz to 125 MHz, MHz-to-kHz Programmable Clo ID Code, 6-Lead SOT-23, Industrial Temp. Range, 3,000/Reel
			N	Note	catalog part nu used for orderin the device pack	identifier only appears in the mber description. This identifier i ng purposes and is not printed o kage. Check with your Microchip r package availability with the option.

NOTES:

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